Unit: mm

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type ($L^2-\pi$ -MOSV)

2SK2233

Chopper Regulator, DC-DC Converter and Motor Drive Applications

• 4 V gate drive

• Low drain-source ON resistance $: RDS(ON) = 0.022 \Omega (typ.)$

• High forward transfer admittance $|Y_{fs}| = 27 \text{ S (typ.)}$

• Low leakage current : $I_{DSS} = 100 \mu A \text{ (max)} \text{ (V}_{DS} = 60 \text{ V)}$

• Enhancement-mode : $V_{th} = 0.8 \sim 2.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA})$

Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit	
Drain-source voltage		V_{DSS}	60	V	
Drain-gate voltage (R _{GS} = 20 kΩ)		V_{DGR}	60	V	
Gate-source voltage		V _{GSS}	±20	V	
Drain current	DC (Note 1)	I _D	45	Α	
	Pulse (Note 1)	I _{DP}	180	Α	
Drain power dissipatio	n (Tc = 25°C)	P _D	100	W	
Single pulse avalanche energy (Note 2)		E _{AS}	246	mJ	
Avalanche current		I _{AR}	45	Α	
Repetitive avalanche energy (Note 3)		E _{AR}	10	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature range		T _{stg}	-55~150	°C	

2-16C1B

Weight: 4.6 g (typ.)

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Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	1.25	°C / W
Thermal resistance, channel to ambient	R _{th (ch-a)}	50	°C/W

Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2: V_{DD} = 25 V, T_{ch} = 25 °C (initial), L = 165 μ H, R_{G} = 25 Ω , I_{AR} = 45 A

Note 3: Repetitive rating: Pulse width limited by maximum channel temperature

This transistor is an electrostatic sensitive device.

Please handle with caution.

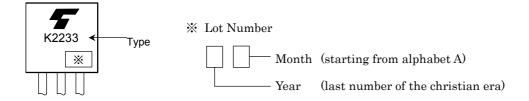
Electrical Characteristics (Ta = 25°C)

Charac	teristics	Symbol	Test Condition	Min	Тур.	Max	Unit	
Gate leakage cu	rrent	I _{GSS}	V _{GS} = ±16 V, V _{DS} = 0 V	_	_	±10	μΑ	
Drain cut-off cur	rent	I _{DSS}	V _{DS} = 60 V, V _{GS} = 0 V	_	_	100	μA	
Drain-source brovoltage	eakdown	V (BR) DSS	I _D = 10 mA, V _{GS} = 0 V	60	_	-	٧	
Gate threshold v	oltage	V _{th}	V _{DS} = 10 V, I _D = 1 mA	0.8	_	2.0	V	
Drain-source ON resistance		R _{DS} (ON)	V _{GS} = 4 V, I _D = 15 A	_	40	55	mΩ	
			V _{GS} = 10 V, I _D = 25 A	_	22	30	11177	
Forward transfer	admittance	Y _{fs}	V _{DS} = 10 V, I _D = 25 A	15	27	_	S	
Input capacitanc	е	C _{iss}		_	1800	_		
Reverse transfer capacitance Output capacitance		C _{rss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz	_	350	_	pF	
		C _{oss}		_	900	_		
Switching time	Rise time	t _r	V _{GS} _{0V} I _D =25A V _{OUT} R _L = 1.2Ω	_	20	_		
	Turn-on time	t _{on}		l	30	l	- ns	
	Fall time	t _f		l	40	ı		
	Turn-off time	t _{off}	$V_{DD} = 30V$ Duty $\leq 1\%$, $t_w = 10 \mu s$	1	130	1		
Total gate charge (Gate-source plus gate-drain)		Qg		_	60	_		
Gate-source charge		Q _{gs}	$V_{DD} \approx 48 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 45 \text{ A}$		40	_	nC	
Gate-drain ("miller") charge		Q _{gd}			20	_		

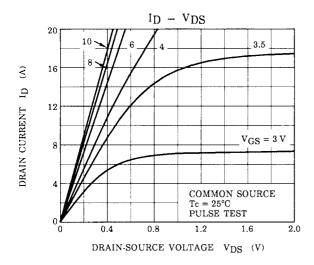
Source-Drain Ratings and Characteristics (Ta = 25°C)

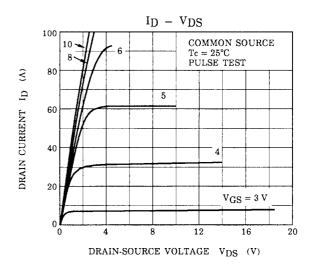
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	_		_	45	Α
Pulse drain reverse current (Note 1)	I _{DRP}	_		_	180	Α
Forward voltage (diode)	V _{DSF}	I _{DR} = 45 A, V _{GS} = 0 V	_	_	-1.8	V
Reverse recovery time	t _{rr}	I _{DR} = 45 A, V _{GS} = 0 V	_	90		ns
Reverse recovered charge	Q _{rr}	dl _{DR} / dt = 100 A / μs		0.1	_	μC

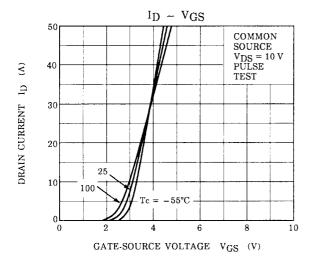
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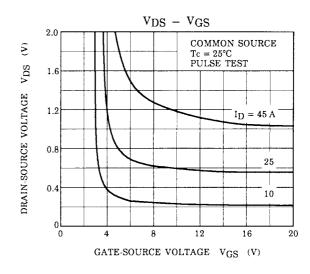


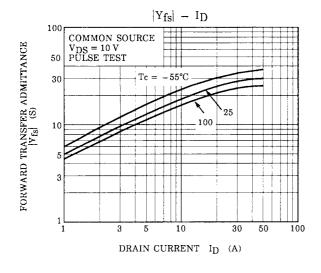
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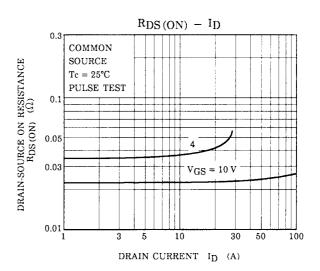




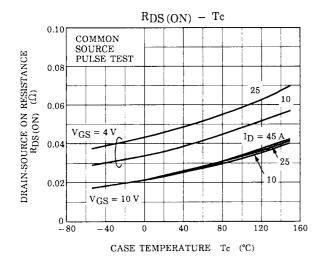


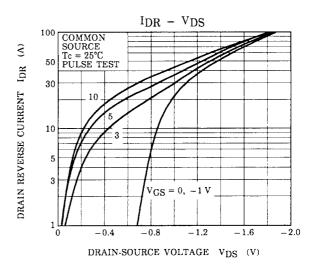


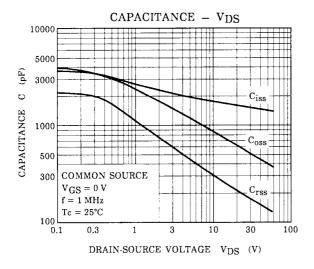


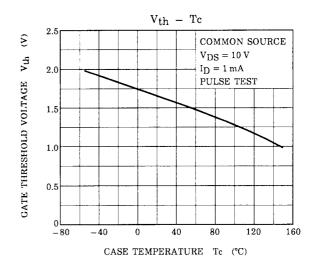


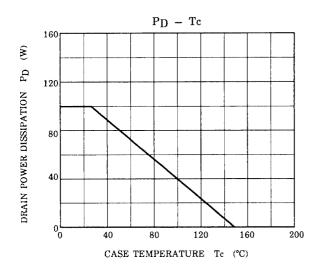
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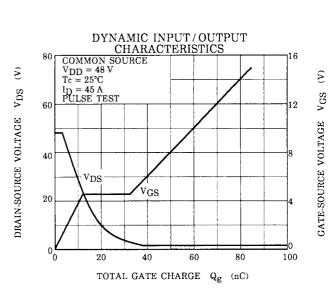




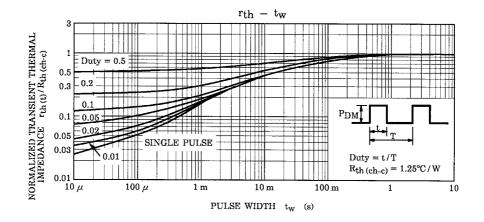


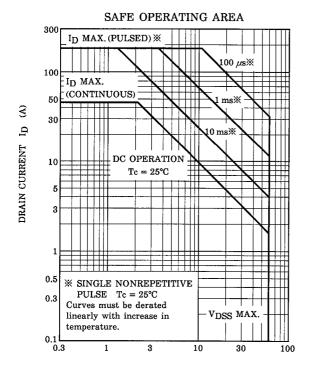


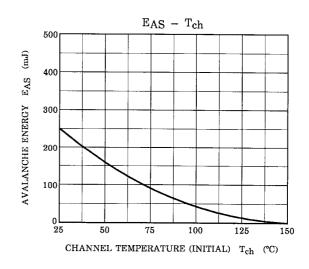


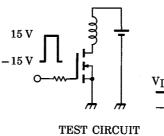


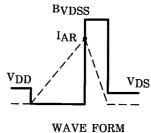
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$$R_G$$
 = 25 Ω
 V_{DD} = 25 V, L = 165 μH

$$E_{AS} = \frac{1}{2} \cdot L \cdot I^{2} \cdot \left(\frac{B_{VDSS}}{B_{VDSS} - V_{DD}} \right)$$

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